MICROWAVE POWER GaAs FET

Internally Matched Power GaAs FETs (C-Band)

Features

- High power
 - P_{1dB} = 36.0 dBm at 3.7 GHz to 4.2 GHz
- High gain
- G_{1dB} = 10.5 dB at 3.7 GHz to 4.2 GHz
 Broad band internally matched
- · Hermetically sealed package

RF Performance Specifications ($T_a = 25^{\circ} C$)

Characteristics	Symbol	Condition	Unit	Min.	Typ.	Мах
Output Power at 1dB Compression Point	P _{1dB}		dBm	35.0	36.0	-
Power Gain at 1dB Compression Point	G _{1dB}	V _{DS} = 10V f = 3.7 ~ 4.2 GHz	dB	9.5	10.5	-
Drain Current	I _{DS}		А	_	1.1	1.5
Power Added Efficiency	η_{add}	-	%	_	33	-
Channel-Temperature Rise	ΔT_{ch}	V _{DS} xI _{DS} xR _{th} (c-c)	°C	-	_	80

Electrical Characteristics ($T_a = 25^{\circ} C$)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Trans-conductance	gm	V _{DS} = 3V I _{DS} = 1.5 A	mS	_	900	-
Pinch-off Voltage	V _{GSoff}	$V_{DS} = 3V$ $I_{DS} = 20mA$	V	-2	-3.5	-5
Saturated Drain Current	I _{DSS}	$V_{DS} = 3V$ $V_{GS} = 0V$	А	-	2.9	3.8
Gate to Source Breakdown Voltage	V _{GSO}	I _{GS} = -60 μA	V	-5	_	_
Thermal Resistance	R _{th (c-c)}	Channel to case	°C/W	_	4.0	6.0

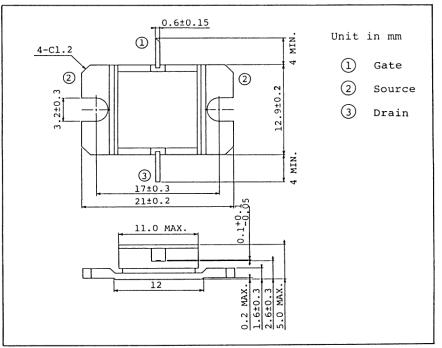
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Absolute Maximum Ratings (Ta = 25° C)

Characteristic	Symbol	Unit	Rating
Drain Source Voltage	V _{DS}	V	15
Gate Source Voltage	V _{GS}	V	-5
Drain Current	I _D	А	4
Total Power Dissipation (Tc = 25°C)	P _T	W	20
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65~175

Package Outline (2-11D1B)

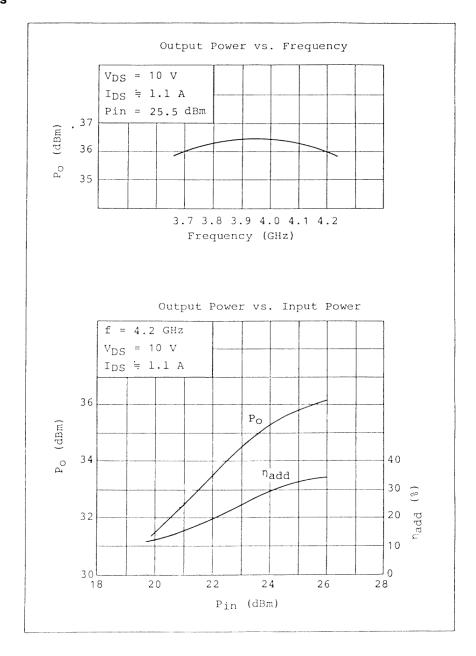


Handling Precautions for Packaged Type

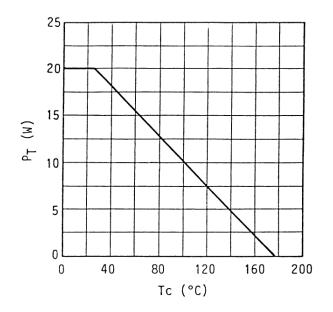
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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RF Performances



Power Dissipation vs. Case Temperature



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TPM3742-4 S-Parameters (MAGN. and ANGLES)

 V_{DS} = 10 V, I_{DS} = 1.0 A f = 3.4 - 4.4 GHz3.8 ↔+90** s₂₁ 60 +0.5 8 4.0 3.4 \$3.6 s₁₂ 4.2 +150° 30° 8 +0.2 S12 .0 4.4<u>A</u> ±180° 0.2 0.1 ٥٥ .8 9 Scale for [S12] 0.2 ŝ 522 . 2 3.6 S21 511 -0.2 -30° -150 for Scale -0.5 - 2 -120 -60* -1 -90° FREQUENCY s₂₂ s₁₁ s₁₂ s₂₁ (GHz) 130 2.98 96 3.77 53 4.28 3.4 0 0.063 178 0.68 50 0.66 0.63 3.6 0.43 -44 0.087 143 26 3.8 0.22 -147 0.107 99 0.46 -10 9 4.12 -30 3.67 -70 3.18 114 0.110 58 0.104 -5 0.095 54 -66 4.0 0.40 0.23 0.52 4.2 13 0.24 -151 4.4 -29 0.41 170